

Polyimide-based microfabrication grade TZ3300

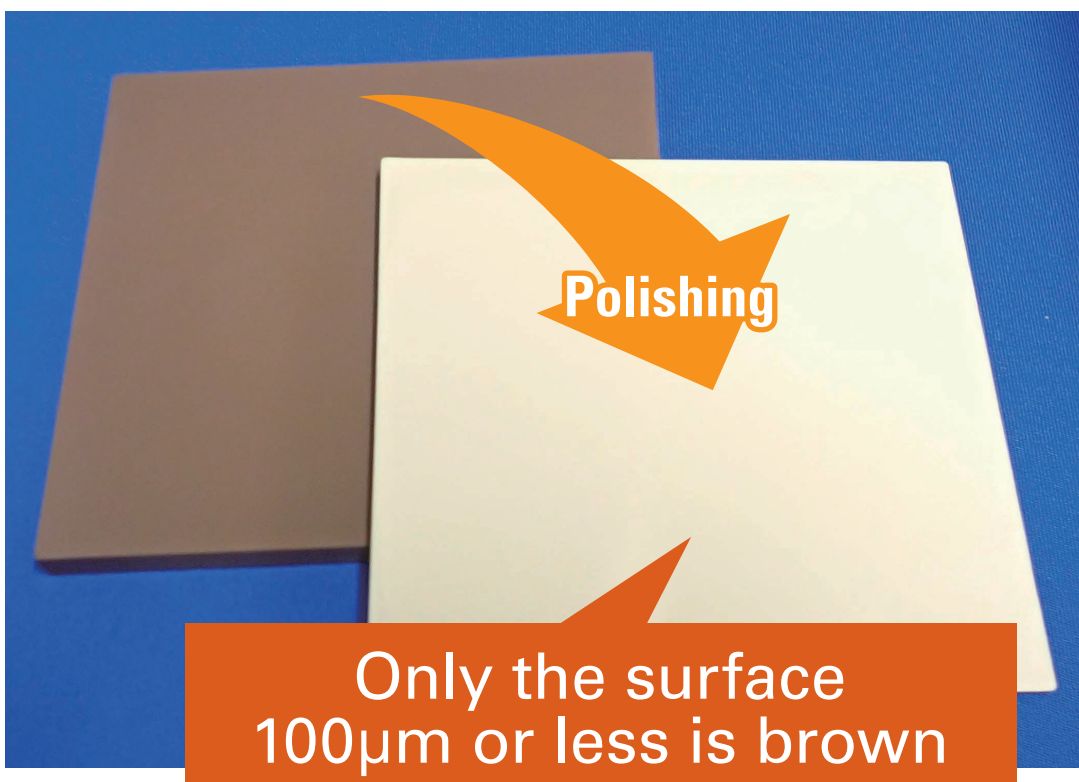
MGC

Ceramic reinforced PI material - Test sockets, probe cards, PCB inspection jigs -

A new resin-based base material with excellent microfabrication and dimensional stability at high temperatures

Characteristic

- Microfabrication of 100μm or less possible
- Drilling and laser processing are possible!
- Less burrs
- Excellent dimensional stability due to the use of highly heat-resistant PI
- Excellent insulation properties, suitable for use with high current devices
- Despite being a PI material, it has low water absorption.



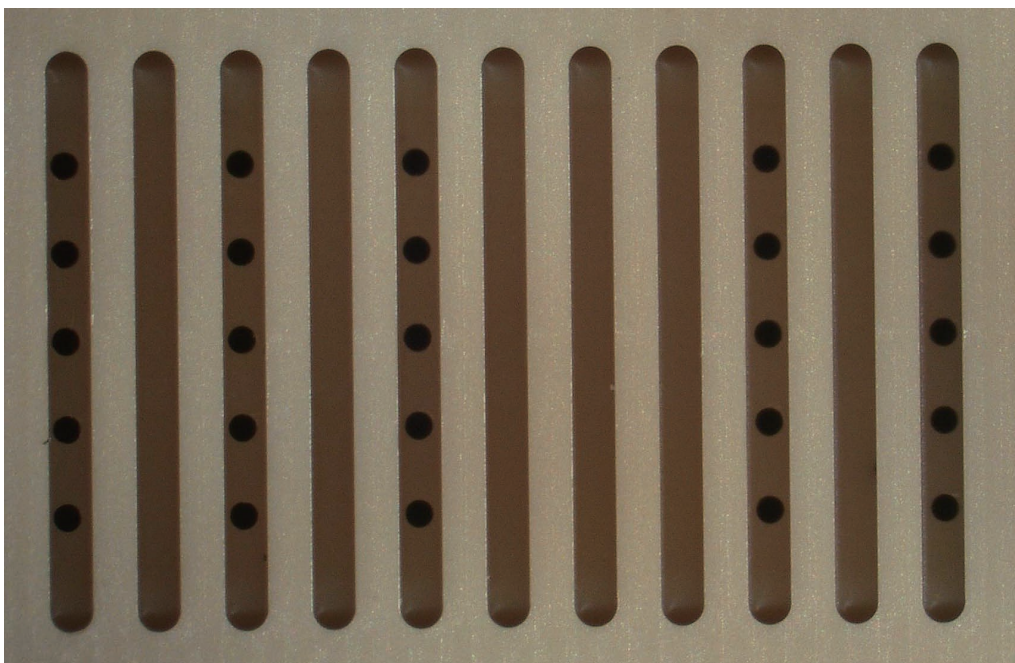
- 70mm square×4mmt
- 100mm square×6mmt
- 200mm square×10mmt
- Thickness adjustable products (>0.4mm) are also available!
- Up to 500mm square also available

Basic Properties

Drilling processability

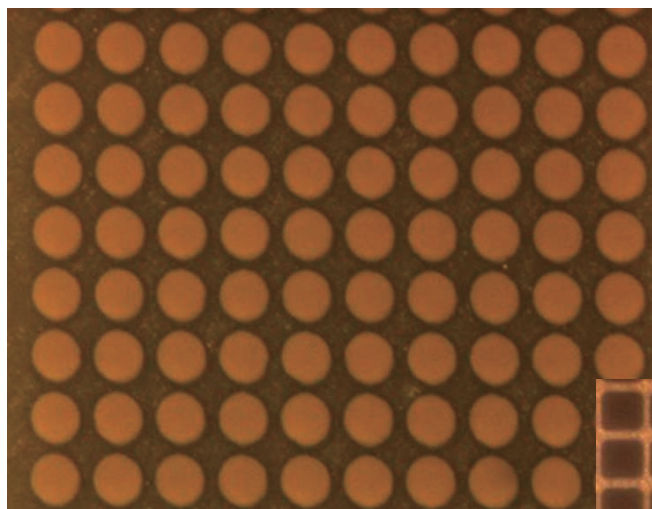


Excellent micromachining and dimensional accuracy



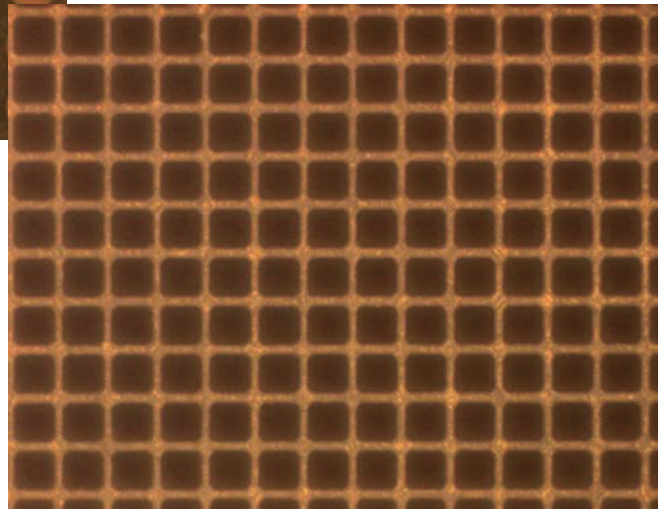
Long holes with a line width of about 120 μm can be processed.

Laser processability



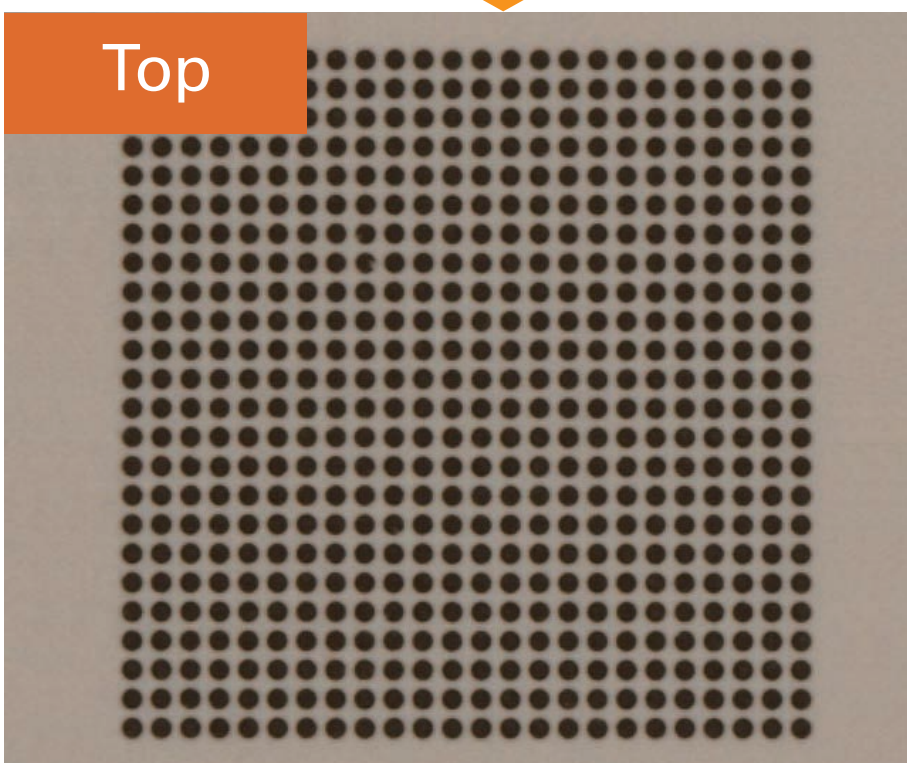
- Φ20μm/pitch 26μm
- No burrs or chips

- 30μm/side
- Bulkhead thickness 7μm
- Rightness of R6

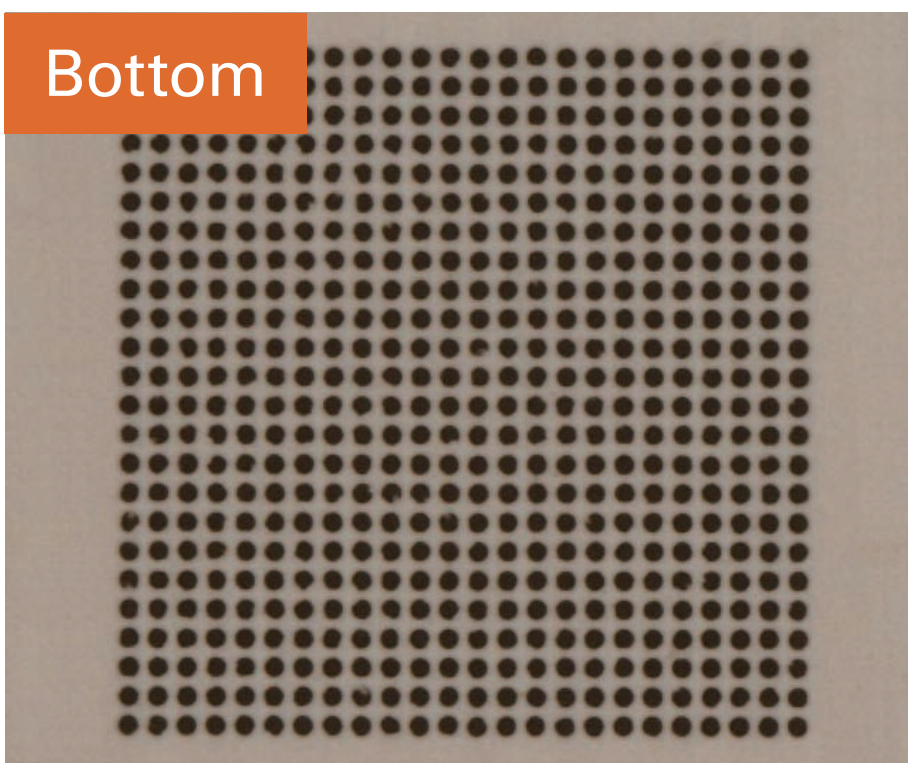


Material properties

	Condition	Unit	TZ3300
Flexural strength		MPa	140
Flexural modulus		GPa	4.4
Rockwell Hardness		—	R125
Dk	10GHz	—	3.4
Df	10GHz	—	0.004
Volume resistivity		Ω・m	4×10 ¹³
Surface Resistivity		Ω	3×10 ¹⁵
CTI		V	600
Water absorption	24h immersion	%	0.06
CTE	50~200℃	ppm	59



φ100μm> Good micro-processability



No bulkhead collapse and little burr

Also suitable for high temperature environments of over 150℃!

